



Material Content Data Sheet



Halogen-Free

Sales Product Name	IR38064MTRPBF	Issued	12. August 2021
MA#	MA005587419		
Package	PG-IQFN-34-900	Weight*	117.91 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	3.900	3.31	3.31	33075	33075
chip_2	inorganic material	silicon	7440-21-3	3.584	3.04	3.04	30396	30396
chip_3	inorganic material	silicon	7440-21-3	1.368	1.16	1.16	11598	11598
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		111	
	non noble metal	zinc	7440-66-6	0.052	0.04		442	
	non noble metal	iron	7439-89-6	1.043	0.88		8842	
	non noble metal	copper	7440-50-8	42.333	35.90	36.83	359041	368436
wire	noble metal	gold	7440-57-5	0.500	0.42	0.42	4238	4238
encapsulation	organic material	carbon black	1333-86-4	0.095	0.08		809	
	plastics	epoxy resin	-	4.915	4.17		41683	
	inorganic material	silicondioxide	60676-86-0	42.705	36.25	40.50	362192	404684
leadfinish	noble metal	palladium	7440-05-3	0.001			12	
	noble metal	gold	7440-57-5	0.002			19	
	non noble metal	nickel	7440-02-0	0.041	0.03	0.03	346	377
plating	noble metal	silver	7440-22-4	0.604	0.51	0.51	5121	5121
solder	non noble metal	tin	7440-31-5	0.250	0.21		2117	
	non noble metal	lead	7439-92-1	4.742	4.02	4.23	40216	42333
heat sink clip	inorganic material	phosphorus	7723-14-0	0.004			30	
	non noble metal	zinc	7440-66-6	0.014	0.01		120	
	non noble metal	iron	7439-89-6	0.282	0.24		2394	
	non noble metal	copper	7440-50-8	11.460	9.72	9.97	97198	99742
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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